			ors
	SPECI	FICATIO	N
宏至	2電子月	26份有	限公司
	桃園縣中	歴市東園路13	3號
	No.13, Dongy	uan Rd., Jhongli	City,
	Taoyuan Count	y 320, Taiwan (R	.O.C.)
		-3-463-2808 -3-463-1800	
SPEC. NO.: PS-5270	8-XXXX-XXX]	REVISION: A
PRODUCT NAME:	0.6mm PITCH	EDGE CARD C	CONN.
	VERTICAL D	/R S/T TYPE.	
PRODUCT NO:	52708 SERIES	6	
PREPARED:	CHECKE	D:	APPROVED:
LIN, CHIA AN	N LE	E, I HUNG	WANG, CHUN SHENG
DATE: 2021/07/23	DATE:	2021/07/23	DATE: 2021/07/23



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3	APPLICABLE DOCUMENTS	4
4	REQUIREMENTS	4
5	PERFORMANCE	5
6	INFRARED REFLOW CONDITION	9
7	PRODUCT QUALIFICATION AND TEST SEQUENCE	10

	1CES			Aces P/N: 52708 SERIES							
TIT	rle: 0.6		DGE CARD	CONN. VER	TICAL D/R S/T TY	PE.					
RELE	RELEASE DATE: 2021/07/23 REVISION: A ECN No: ECN-003369 PAGE: 3 OF 10										
1	Revisic	on History									
	Rev.	ECN #		Revision De	scription	Prepared	Date				
	Α	ECN-003369	NEW PRO	DUCT RELEAS	CA.LIN	2021/07/23					

	ACES		А	Aces P/N:	52708 SERIE	ES	
Т	ITLE: 0.6M	M PITCH	EDGE CARD CO	ONN. VEF	RTICAL D/R S/	T TYPE.	
REL	EASE DATE: 20	21/07/23	REVISION: A		ECN No: ECN-003	3369	PAGE: 4 OF 10
2			overs performan SE CARD CONN				
3	APPLICA		CUMENTS				
		Electrical co	ammability for Pla onnector/Socket To ocol Agnostic Mult	est Procec	lures Including E	Environment	
4	REQUIRE	EMENTS					
	4.1 Design	and Constr	ruction				
	4.1.1	applicabl	shall be of design, e product drawing	.			
	4.1.2		ials conform to R.o	o.H.S. and	I the standard de	epends on I	Q-WI-140101.
	4.2 Materia	ls and Finis	sh				
	4.2.1	Contact: H Finish:	igh performance c (a) Contact Area: (b) Under plate: I (c) Solder area: I	Refer to t Refer to th	he drawing. e drawing.	onze)	
			Thermoplastic or T yester., UL94V-0			, UL94V-0	
		Fit Nail: H	igh performance a	•		el)	
		Finish:	(a) Under plate: (b) Solder area:				
	4.3 Ratings	i					
		•	Temperature : -40 anditions: -5°C to +			RH;	

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Ι.



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5 Performance

5.1. Test Requirements and Procedures Summary

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ltem	Requirement	Standard							
Examination of Product	Product shall meet requirements of applicable product drawing and specification.	Visual, dimensional and functional per applicable quality inspection plan.							
ELECTRICAL									
ltem	Requirement	Standard							
Low Level Contact Resistance	Initial: 30 m Ω Max. After test: $\triangle 15$ m Ω Max	Mate connectors, measure by dry circuit, 20mV Max., 100mA Max. (EIA-364-23)							
Insulation Resistance	1000 MΩ Min.	After 100 VDC for 1 minute, measure the insulation resistance between the adjacent contacts of unmated connector assemblies. (EIA-364-21)							
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 0.5 mA max.	300 VAC Min. at sea level for 1 minute. Test between adjacent contacts of unmated connectors. (EIA-364-20C Method B)							
Temperature Rise	30℃ Max. Change allowed	Voltage Rating: 30V Current Rating: 1.1A Mate connectors: measure the temperature rise at rated current until temperature stable. The ambient condition is still air at 25°C. Total 12 pins must be tested. Meanwhile, the test positions are A1 to A6 and B1 to B6. (EIA-364-70)							



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MECHANICAL							
ltem	Requirement	Standard					
Durability	200 Cycles for 30u" Au 100 Cycles for 15u" Au 50 Cycles for Gold flash After test: <u>Δ15 mΩ</u> Max. change allowed	The sample should be mounted in the tester and fully mated and unmated the number of cycles. (EIA-364-09)					
Durability(precondition)	Perform 5 mate/unmate cycles.	No evidence of physical damage (EIA-364-09)					
Mating Un-mating Force (Module only)	Mating Force: 1.1N Max. per pair pin Un-mating Force: 0.1N Min. per pair pin	Measure the force required to mate/unmate connector. (EIA-364-13)					
Active Latch Retention Strength	50 N minimum	EIA-364-13 Rate: 25.4 mm/minute					
Wrenching strength (W/ mated Cable- Passive Latch)	25 N minimum	Bend cable 90° at minimum bend radius. Pull in 4 axis directions for round cable. Pull in 2 axis directions for flat cable.					
Wrenching strength (W/ mated Cable- Active Latch)	40 N minimum	No damage to plug/ cable assembly. Bend cable 90° at minimum bend radius. Pull in 4 axis directions for round cable. Pull in 2 axis directions for flat cable. No damage to plug/ cable assembly.					
Contact & Fit Nail Retention	Retention Force: 3.0 N Min.	Measure the retention force of contact and Fit Nail in the housing. (EIA-364-29)					
Vibration	No discontinuities of ≥ 1 microsecond electrical, mechanical and environmental criteria	Random profile: 5 Hz @ 0.01 g2/Hz to 20Hz @ 0.02 g2/Hz(slope up) 20 Hz to 500 Hz @ 0.02 g2/Hz (flat) Input acceleration is 3.13 g RMS. 10 minutes per axis for all 3 axes on all samples Random control limit tolerance is ± 3 dB. (EIA-364-28)					
Mechanical Shock	No discontinuity longer than 1 microsecond allowed.	Subject mated specimens to 50G's half-sine shook pulses of 11 milliseconds duration 3 shocks in each direction applied along 3 mutually perpendicular planes, 18 total shocks. (EIA-364-27)					
Resistance to Reflow Soldering Heat	No discharge	Pre Heat : 150°C~180°C, 60~120sec. Heat : 230°C Min., 40sec Min. Peak Temp. : 260°C Max, 10sec Max.					

Connectors		Aces P/N: 5	2708 SI	ERIES	
TITLE: 0.6MM PITCH EDG	E CARD C	ONN. VER		/R S/T TYPE.	
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Reseating	Appearanc	ce: No damag	je	Manually mated/ connector or soc cycles.	unmated the ket perform 3

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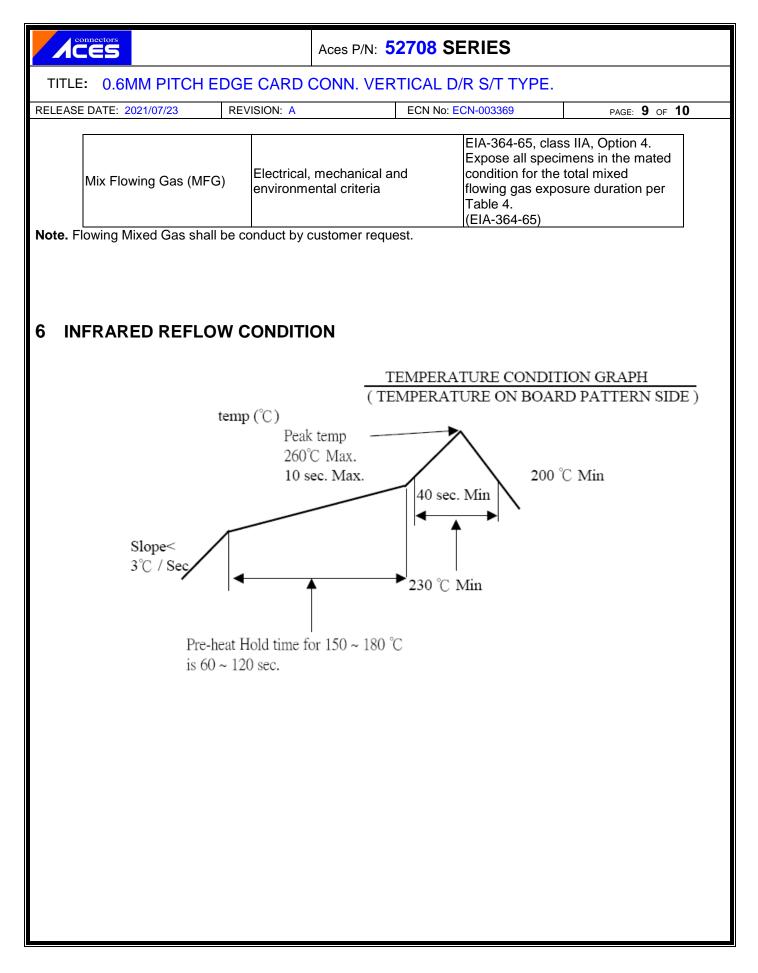
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ENVIRONMENTAL							
ltem	Requirement	Standard					
Thermal Shock	See Product Qualification and Test Sequence Group <mark>5</mark>	Mate module and subject to follow condition for 100 cycles. 1 cycles: -55°C and +85 °C each 30min. (EIA-364-32,Test condition I)					
		60 °C field temperature. Test					
Temperature Life	No physical damage	Temperature and Test Duration per EIA 364-1000 Table 8 (EIA-364-17)					
Temperature Life (precondition)	No physical damage	60 °C field temperature. Test Temperature and Test Duration per EIA 364-1000 Table 9 (EIA-364-17)					
Thermal Disturbance	No physical damage	Test condition : Cycle the connector between $15^{\circ}C \pm 3^{\circ}C$ and $85^{\circ}C \pm 3^{\circ}C$, Humidity is not controlled Test Duration : Ramps should be a minimum of 2 °C per minute, and dwell times should insure that the contacts reach the temperature extremes (a minimum of 5 inutes) Number of cycles: Perform 10 such cycles (EIA-364-1000)					
Salt Spray	See Product Qualification and Test Sequence Group 1	Subject mated connectors to 5% salt-solution concentration, 35°C Gold plating 30 u" for 96 hours. (EIA-364-26)					
Humidity-Temperature Cycling	No Physical damage	Test condition : Method III without conditioning Cycle the connector between 25 °C \pm 3 °C at 80 % \pm 3% RH and 65 °C \pm 3 °C at 50 % \pm 3% RH. Ramp times should be 0.5 hour and dwell times should be 1.0 hour Test Duration : 24 hours per cycle Number of cycles: Perform 24 continuous cycles (EIA-364-31)					
Solder Ability	Tin plating: Solder able area shall have minimum of 95% solder coverage. Gold plating: Solder able area shall have minimum of 75% solder coverage	Add then into solder bath, Temperature at 245 ±5°C, for 4-5 sec. (EIA-364-52)					



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PRODUCT QUALIFICATION AND TEST SEQUENCE 7

Test or Examination							Group					
	1	2	3	4	5	6 est Se	7 quence	8 e	9	10	11	12
Examination of Product	1,8	1,10	1,10	1,12	1,8,12	1,3	1,3	1,3	1,3	1,3	1,3	1,3
Low Level Contact Resistance	2,5,7	2,5, 7,9	2,5, 7,9	2,5,7 ,9,11	2,9							
Insulation Resistance					3,10							
Dielectric Withstanding Voltage					4,11							
Temperature Rise						2						
Durability					6							
Durability(precondition)	3	3	3	3								
Mating / Unmating Forces					5,7							
Contact & Fit Nail Retention							2					
Vibration			6									
Mechanical Shock			8									
Resistance to Reflow Soldering Heat										2		
Reseating	6	8		10								
Thermal Shock		4										
Thermal Disturbance				8								
Temperature Life	4											
Temperature Life (precondition)			4	4								
Salt Spray								2				
Humidity-Temperature Cycling		6										
Solder Ability									2			
Mix Flowing Gas (MFG)				6								
Wrenching strength (W/mated cable-passive Latch)											2	
Wrenching strength (W/mated cable-active Latch)												2
Sample Size	5	5	5	5	5	5	5	5	5	5	3	3